

What is claimed is:

1. An electronic module comprising:

an electroluminescent section;

5 a first substrate on which the electroluminescent section is formed;

a second substrate attached to the first substrate;

an integrated circuit chip mounted on the second substrate; and

a plurality of power supply interconnects for allowing current to flow through
the electroluminescent section,

10 wherein the power supply interconnects include: a plurality of first power supply
interconnects formed on the first substrate, extending through a pair of regions located
on both sides of the electroluminescent section; and a plurality of second power supply
interconnects formed on the second substrate, extending through a pair of regions
located on both sides of the integrated circuit chip, the first and second power supply
15 interconnects being electrically connected.

2. The electronic module as defined by claim 1, further comprising:

a plurality of signal interconnects for inputting a drive signal from the integrated
circuit chip to the electroluminescent section,

20 wherein the signal interconnects are formed in a region interposing between a
first region in which one part of the power supply interconnects are formed and a
second region in which the other part of the power supply interconnects are formed.

3. The electronic module as defined by claim 2, wherein width of each of the
25 signal interconnects is narrower than width of each of the power supply interconnects.

4. The electronic module as defined by claim 2, further comprising:

a pair of scanning drivers disposed on both sides of the electroluminescent section, respectively, on the first substrate; and

a plurality of control interconnects for inputting a control signal from the integrated circuit chip to each of the scanning drivers,

5 wherein the control interconnects are formed in a pair of regions which are located on both sides of a region in which the signal interconnects are formed and interpose between the first region and the second region.

5. The electronic module as defined by claim 1, further comprising:

10 a plurality of connector terminals formed on an end portion of the second substrate except a portion to which the first substrate is attached,

wherein width of each of the connector terminals is formed to be wider than width of each of the power supply interconnects.

15 6. An electronic instrument comprising the electronic module as defined by claim 1.

7. A method of manufacturing an electronic module comprising:

20 fixing a first substrate, on which an electroluminescent section is formed, with a second substrate on which an integrated circuit chip is mounted,

wherein the first substrate includes a plurality of first power supply interconnects which are formed extending through a pair of regions located on both sides of the electroluminescent section,

25 wherein the second substrate includes a plurality of second power supply interconnects which are formed extending through a pair of regions located on both sides of the integrated circuit chip, and

wherein the first and second power supply interconnects are electrically

connected in the step of fixing the first and second substrate.

8. An electronic module comprising:

an electronic substrate including a plurality of first terminals;

5 an interconnect substrate on which an interconnect pattern is formed, the
interconnect pattern including a plurality of second terminals electrically connected
with the first terminals of the electronic substrate, at least two first interconnects
extending from at least two of the second terminals, and at least two second
interconnects formed in a state to be electrically insulated from the first interconnects;

10 and

an electrical connection section which electrically connects at least one of the
first interconnects with at least one of the second interconnects.

9. The electronic module as defined by claim 8, further comprising:

15 an integrated circuit chip mounted on the interconnect substrate,
wherein the second interconnects are electrically connected with the integrated
circuit chip.

10. The electronic module as defined by claim 9,

20 wherein the electrical connection section is provided at a position closer to the
electronic substrate than the integrated circuit chip.

11. The electronic module as defined by claim 9,

25 wherein the electrical connection section is provided in each of a pair of regions
respectively located closer to both ends of the interconnect substrate than a center of the
interconnect substrate in a widthwise direction.

12. An electronic instrument comprising the electronic module as defined by claim 8.

13. A method of manufacturing an electronic module comprising:

5 electrically connecting a plurality of first terminals of an electronic substrate with a plurality of second terminals of an interconnect substrate; and

electrically connecting at least one of two or more first interconnects extending from two or more of the second terminals with at least one of two or more second interconnects formed in a state to be electrically insulated from the first interconnects,
10 by means of an electrical connection section.

14. An electronic module comprising:

an electronic substrate; and

an interconnect substrate which is attached to the electronic substrate and on
15 which an integrated circuit chip is mounted,

wherein the interconnect substrate includes an input terminal and one or more amplifier circuits, each of the amplifier circuits generating a plurality of different amplified power supplies by amplifying an external power supply input to the input terminal.

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15. The electronic module as defined by claim 14,

wherein the integrated circuit chip is driven by the external power supply, and

wherein the electronic substrate is driven by the amplified power supplies.

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16. The electronic module as defined by claim 14, wherein the amplifier circuit is formed in a region between the integrated circuit chip and the input terminal.

17. The electronic module as defined by claim 14,
wherein the integrated circuit chip is mounted at a center of the interconnect
substrate in a widthwise direction, and

wherein a pair of the amplifier circuits are respectively formed on both end
5 portions of the interconnect substrate in the widthwise direction.

18. The electronic module as defined by claim 17,

wherein the interconnect substrate includes:

signal interconnects which extend from the integrated circuit chip toward the
10 electronic substrate; and

power supply interconnects which extend from the pair of amplifier circuits
toward the electronic substrate, and

wherein the power supply interconnects are formed to be wider than the signal
interconnects.

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19. The electronic module as defined by claim 14,

wherein one of the amplifier circuits includes a first circuit and a second circuit,
the first circuit being formed on the integrated circuit chip, and a second circuit being
provided separately from the integrated circuit chip.

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20. The electronic module as defined by claim 19, wherein the second circuit
includes a capacitor.

21. The electronic module as defined by claim 19, wherein the second circuit
25 includes an inductor.

22. An electronic instrument comprising the electronic module as defined by

claim 14.

23. A method of driving an electronic module comprising:

inputting an external power supply to an input terminal formed on an
5 interconnect substrate on which an integrated circuit chip is mounted;

generating a plurality of different amplified power supplies by amplifying the
external power supply by using one or more amplifier circuits formed on the
interconnect substrate; and

driving an electronic substrate electrically connected with the interconnect
10 substrate by using the plurality of different amplified power supplies.